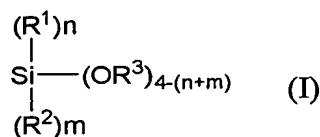
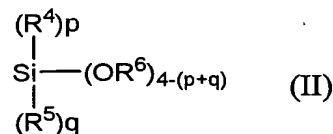


Abstract

A coating composition for forming a silica-containing film comprises
(A) a hydrolyzate and/or partially condensed product of a compound
5 represented by the following general formula (I) and a compound
represented by the following general formula (II):



wherein R^1 represents a hydrogen atom, an alkyl group or an aryl group; R^2
represents an organic group having an unsaturated bond; R^3 represents an
10 alkyl group; n ranges from 0 to 2; m ranges from 1 to 3, provided that $0 \leq n +$
 $m \leq 3$; and



wherein R^4 represents an alkyl group or an aryl group; R^5 represents a
hydrogen atom; R^6 represents an alkyl group; and p and q are integers
15 satisfying the relation: $0 \leq p + q \leq 3$; (B) a solvent for coating; and (C) at least
one member selected from the group consisting of a void-forming solvent, a
compound having a polyalkylene oxide structure and hollow polymer fine
particles. The silica-containing film obtained from the composition is
excellent in the heat resistance, adhesive properties and resistance to
20 cracking and has a low dielectric constant. Accordingly, the composition is
suitable used as a material for forming an interlayer insulating film in the
field of, for instance, semiconductor elements.